



25AA640/25LC640

64K SPI™ Bus Serial EEPROM

Device Selection Table

Part Number	Vcc Range	Max Clock Frequency	Temp Ranges
25AA640	1.8-5.5V	1 MHz	I
25LC640	2.5-5.5V	2 MHz	I
25LC640	4.5-5.5V	3/2.5 MHz	I, E

Features

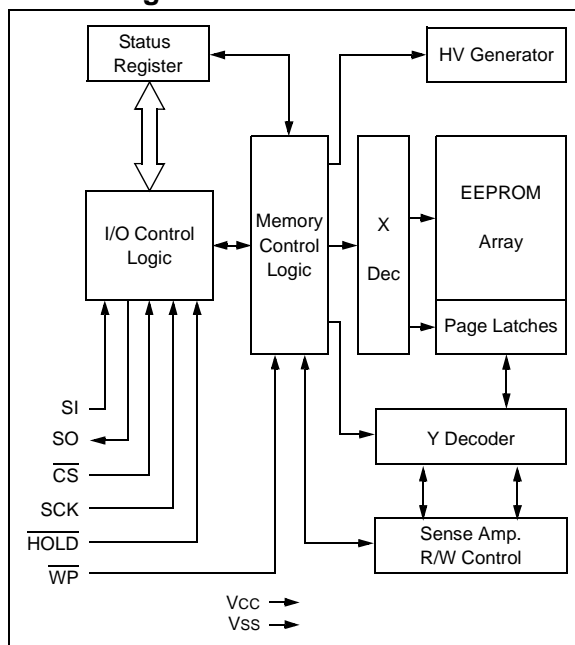
- Low power CMOS technology
 - Write current: 3 mA typical
 - Read current: 500 μ A typical
 - Standby current: 500 nA typical
- 8192 x 8 bit organization
- 32 byte page
- Write cycle time: 5 ms max.
- Self-timed ERASE and WRITE cycles
- Block write protection
 - Protect none, 1/4, 1/2 or all of array
- Built-in write protection
 - Power on/off data protection circuitry
 - Write enable latch
 - Write protect pin
- Sequential read
- High reliability
 - Data retention: > 200 years
 - ESD protection: > 4000V
- 8-pin PDIP, SOIC and TSSOP packages
 - Industrial (I): -40°C to +85°C
 - Automotive (E): -40°C to +125°C

Description

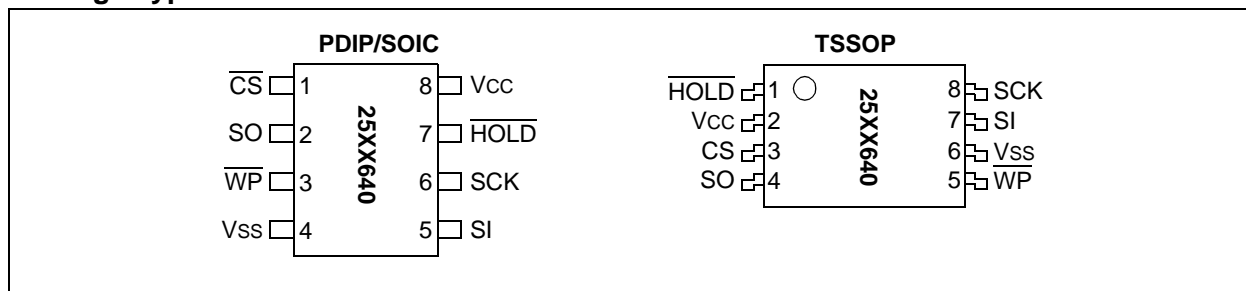
The Microchip Technology Inc. 25AA640/25LC640 (25XX640*) is a 64K bit Serial Electrically Erasable PROM [EEPROM]. The memory is accessed via a simple Serial Peripheral Interface (SPI) compatible serial bus. The bus signals required are a clock input (SCK) plus separate data in (SI) and data out (SO) lines. Access to the device is controlled through a chip select (\overline{CS}) input.

Communication to the device can be paused via the hold pin (HOLD). While the device is paused, transitions on its inputs will be ignored, with the exception of chip select, allowing the host to service higher priority interrupts.

Block Diagram



Package Types



*25XX640 is used in this document as a generic part number for the 25AA640/25LC640 devices.

25AA640/25LC640

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

VCC.....	7.0V
All inputs and outputs w.r.t. VSS	-0.6V to VCC+1.0V
Storage temperature	-65°C to 150°C
Ambient temperature under bias	-65°C to 125°C
Soldering temperature of leads (10 seconds)	+300°C
ESD protection on all pins	4 kV

† NOTICE: Stresses above those listed under 'Maximum ratings' may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for an extended period of time may affect device reliability.

1.1 DC Characteristics

DC Characteristics			Industrial (I): T _{AMB} = -40°C to +85°C V _{CC} = 1.8V to 5.5V Automotive (E): T _{AMB} = -40°C to +125°C V _{CC} = 4.5V to 5.5V			
Param. No.	Sym	Characteristics	Min	Max	Units	Conditions
D1	V _{IH1}	High level input voltage	2.0	V _{CC} +1	V	V _{CC} ≥ 2.7V (Note)
D2	V _{IH2}		0.7 V _{CC}	V _{CC} +1	V	V _{CC} < 2.7V (Note)
D3	V _{IL1}	Low level input voltage	-0.3	0.8	V	V _{CC} ≥ 2.7V (Note)
D4	V _{IL2}		-0.3	0.2 V _{CC}	V	V _{CC} < 2.7V (Note)
D5	V _{OL}	Low level output voltage	—	0.4	V	I _{OL} = 2.1 mA
			—	0.2	V	I _{OL} = 1.0 mA, V _{CC} = < 2.5V
D6	V _{OH}	High level output voltage	V _{CC} -0.5	—	V	I _{OH} = -400 μA
D7	I _{LI}	Input leakage current	-10	10	μA	\overline{CS} = V _{CC} , V _{IN} = V _{SS} TO V _{CC}
D8	I _{LO}	Output leakage current	-10	10	μA	\overline{CS} = V _{CC} , V _{OUT} = V _{SS} TO V _{CC}
D9	C _{INT}	Internal Capacitance (all inputs and outputs)	—	7	pF	T _{AMB} = 25°C, CLK = 1.0 MHz, V _{CC} = 5.0V (Note)
D10	I _{CC} Read	Operating Current	—	1	mA	V _{CC} = 5.5V; F _{CLK} = 3.0 MHz; SO = Open
			—	500	μA	V _{CC} = 2.5V; F _{CLK} = 2.0 MHz; SO = Open
D11	I _{CC} Write		—	5	mA	V _{CC} = 5.5V
			—	3	mA	V _{CC} = 2.5V
D12	I _{CCS}	Standby Current	—	5	μA	\overline{CS} = V _{CC} = 5.5V, Inputs tied to V _{CC} or V _{SS}
			—	1	μA	\overline{CS} = V _{CC} = 2.5V, Inputs tied to V _{CC} or V _{SS}

Note: This parameter is periodically sampled and not 100% tested.

25AA640/25LC640

1.2 AC Characteristics

AC Characteristics			Industrial (I): T _{AMB} = -40°C to +85°C V _{CC} = 1.8V to 5.5V Automotive (E): T _{AMB} = -40°C to +125°C V _{CC} = 4.5V to 5.5V			
Param. No.	Sym	Characteristic	Min	Max	Units	Conditions
1	FCLK	Clock Frequency	—	3	MHz	V _{CC} = 4.5V to 5.5V (Note 2)
			—	2	MHz	V _{CC} = 2.5V to 5.5V
			—	1	MHz	V _{CC} = 1.8V to 5.5V
2	T _{CSS}	$\overline{\text{CS}}$ Setup Time	100	—	ns	V _{CC} = 4.5V to 5.5V
			250	—	ns	V _{CC} = 2.5V to 5.5V
			500	—	ns	V _{CC} = 1.8V to 5.5V
3	T _{CSH}	$\overline{\text{CS}}$ Hold Time	150	—	ns	V _{CC} = 4.5V to 5.5V
			250	—	ns	V _{CC} = 2.5V to 5.5V
			475	—	ns	V _{CC} = 1.8V to 5.5V
4	T _{CSD}	$\overline{\text{CS}}$ Disable Time	500	—	ns	
5	T _{SU}	Data Setup Time	30	—	ns	V _{CC} = 4.5V to 5.5V
			50	—	ns	V _{CC} = 2.5V to 5.5V
			50	—	ns	V _{CC} = 1.8V to 5.5V
6	T _{HD}	Data Hold Time	50	—	ns	V _{CC} = 4.5V to 5.5V
			100	—	ns	V _{CC} = 2.5V to 5.5V
			100	—	ns	V _{CC} = 1.8V to 5.5V
7	T _R	CLK Rise Time	—	2	μs	(Note 1)
8	T _F	CLK Fall Time	—	2	μs	(Note 1)
9	T _{HI}	Clock High Time	150	—	ns	V _{CC} = 4.5V to 5.5V
			230	—	ns	V _{CC} = 2.5V to 5.5V
			475	—	ns	V _{CC} = 1.8V to 5.5V
10	T _{LO}	Clock Low Time	150	—	ns	V _{CC} = 4.5V to 5.5V
			230	—	ns	V _{CC} = 2.5V to 5.5V
			475	—	ns	V _{CC} = 1.8V to 5.5V
11	T _{CLD}	Clock Delay Time	50	—	ns	
12	T _{CLE}	Clock Enable Time	50	—	ns	
13	T _V	Output Valid from Clock Low	—	150	ns	V _{CC} = 4.5V to 5.5V
			—	230	ns	V _{CC} = 2.5V to 5.5V
			—	475	ns	V _{CC} = 1.8V to 5.5V
14	T _{HO}	Output Hold Time	0	—	ns	(Note 1)
15	T _{DIS}	Output Disable Time	—	200	ns	V _{CC} = 4.5V to 5.5V (Note 1)
			—	250	ns	V _{CC} = 2.5V to 5.5V (Note 1)
			—	500	ns	V _{CC} = 1.8V to 5.5V (Note 1)
16	T _{HS}	$\overline{\text{HOLD}}$ Setup Time	100	—	ns	V _{CC} = 4.5V to 5.5V
			100	—	ns	V _{CC} = 2.5V to 5.5V
			200	—	ns	V _{CC} = 1.8V to 5.5V
17	T _{HH}	$\overline{\text{HOLD}}$ Hold Time	100	—	ns	V _{CC} = 4.5V to 5.5V
			100	—	ns	V _{CC} = 2.5V to 5.5V
			200	—	ns	V _{CC} = 1.8V to 5.5V
18	T _{HZ}	$\overline{\text{HOLD}}$ Low to Output High-Z	100	—	ns	V _{CC} = 4.5V to 5.5V (Note 1)
			150	—	ns	V _{CC} = 2.5V to 5.5V (Note 1)
			200	—	ns	V _{CC} = 1.8V to 5.5V (Note 1)
19	T _{HV}	$\overline{\text{HOLD}}$ High to Output Valid	100	—	ns	V _{CC} = 4.5V to 5.5V
			150	—	ns	V _{CC} = 2.5V to 5.5V
			200	—	ns	V _{CC} = 1.8V to 5.5V
20	T _{WC}	Internal Write Cycle Time	—	5	ms	
21	—	Endurance	100 k	—	E/W Cycles	(Note 3)

Note 1: This parameter is periodically sampled and not 100% tested.

Note 2: FCLK max. = 2.5 MHz for T_{AMB} > 85°C.

Note 3: This parameter is not tested but established by characterization. For endurance estimates in a specific application, please consult the Total Endurance Model which can be obtained on our website.

FIGURE 1-1: HOLD TIMING

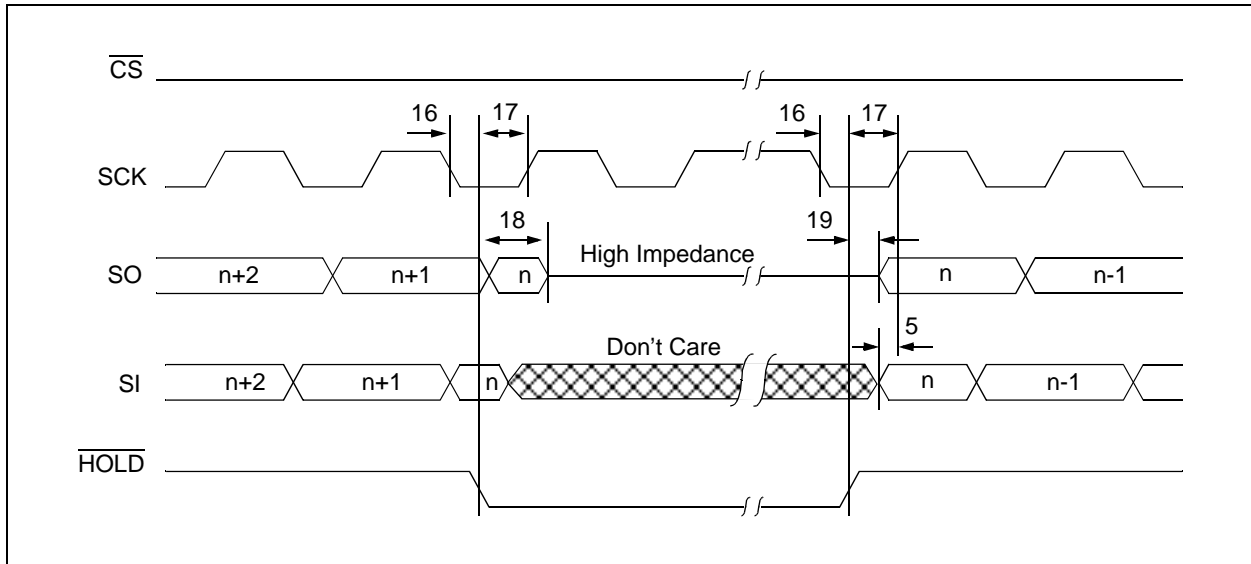


FIGURE 1-2: SERIAL INPUT TIMING

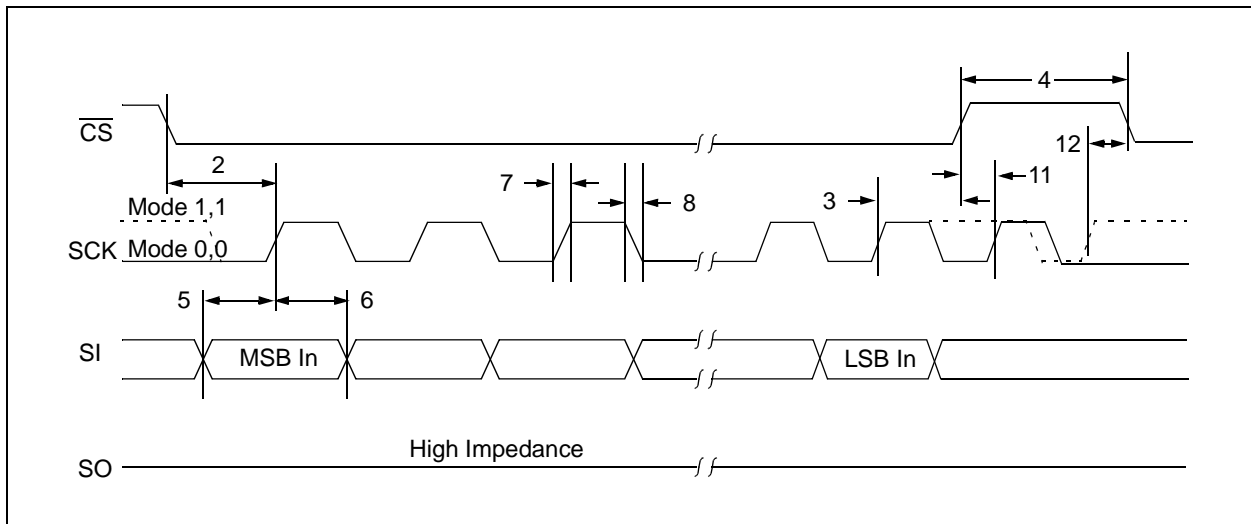
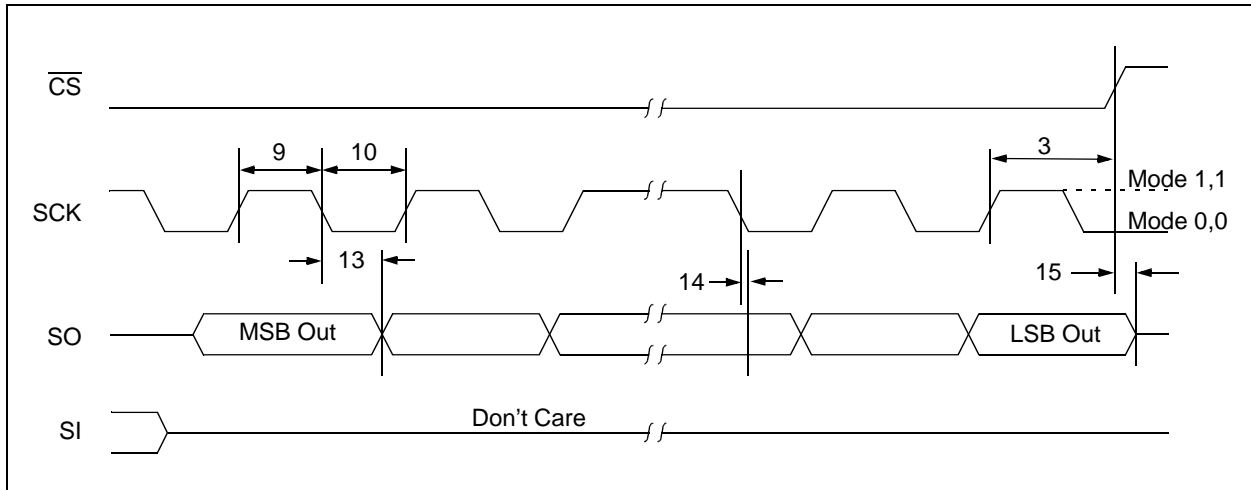


FIGURE 1-3: SERIAL OUTPUT TIMING



25AA640/25LC640

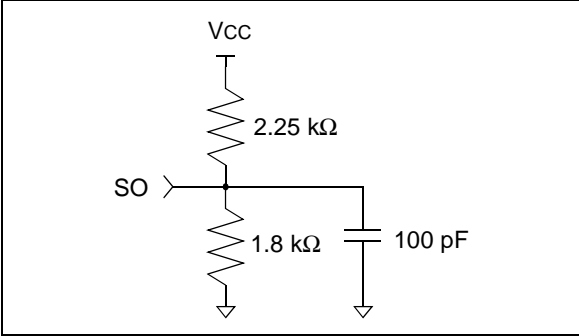
1.3 AC Test Conditions

AC Waveform:	
VLO = 0.2V	
VHI = VCC - 0.2V	(Note 1)
VHI = 4.0V	(Note 2)
Timing Measurement Reference Level	
Input	0.5 VCC
Output	0.5 VCC

Note 1: For $V_{CC} \leq 4.0V$

2: For $V_{CC} > 4.0V$

FIGURE 1-4: AC TEST CIRCUIT



2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

Name	PDIP	SOIC	TSSOP	Description
\overline{CS}	1	1	3	Chip Select Input
SO	2	2	4	Serial Data Output
\overline{WP}	3	3	5	Write Protect Pin
Vss	4	4	6	Ground
SI	5	5	7	Serial Data Input
SCK	6	6	8	Serial Clock Input
\overline{HOLD}	7	7	1	Hold Input
Vcc	8	8	2	Supply Voltage

2.1 Chip Select (\overline{CS})

A low level on this pin selects the device. A high level deselects the device and forces it into standby mode. However, a programming cycle which is already initiated or in progress will be completed, regardless of the \overline{CS} input signal. If \overline{CS} is brought high during a program cycle, the device will go into standby mode when the programming cycle is complete. When the device is deselected, SO goes to the high impedance state, allowing multiple parts to share the same SPI bus. A low to high transition on \overline{CS} after a valid write sequence initiates an internal write cycle. After power-up, a high to low transition on \overline{CS} is required prior to any sequence being initiated.

2.2 Serial Output (SO)

The SO pin is used to transfer data out of the 25XX640. During a read cycle, data is shifted out on this pin after the falling edge of the serial clock.

2.3 Write Protect (\overline{WP})

This pin is used in conjunction with the WPEN bit in the status register to prohibit writes to the non-volatile bits in the status register. When \overline{WP} is low and WPEN is high, writing to the non-volatile bits in the status register is disabled. All other operations function normally. When \overline{WP} is high, all functions, including writes to the non-volatile bits in the status register operate normally. If the WPEN bit is set, \overline{WP} low during a status register write sequence will disable writing to the status register. If an internal write cycle has already begun, \overline{WP} going low will have no effect on the write.

The \overline{WP} pin function is blocked when the WPEN bit in the status register is low. This allows the user to install the 25AA640/25LC640 in a system with \overline{WP} pin grounded and still be able to write to the status register. The \overline{WP} pin functions will be enabled when the WPEN bit is set high.

2.4 Serial Input (SI)

The SI pin is used to transfer data into the device. It receives instructions, addresses, and data. Data is latched on the rising edge of the serial clock.

2.5 Serial Clock (SCK)

The SCK is used to synchronize the communication between a master and the 25XX640. Instructions, addresses, or data present on the SI pin are latched on the rising edge of the clock input, while data on the SO pin is updated after the falling edge of the clock input.

2.6 Hold (\overline{HOLD})

The \overline{HOLD} pin is used to suspend transmission to the 25XX640 while in the middle of a serial sequence without having to re-transmit the entire sequence over again. It must be held high any time this function is not being used. Once the device is selected and a serial sequence is underway, the \overline{HOLD} pin may be pulled low to pause further serial communication without resetting the serial sequence. The \overline{HOLD} pin must be brought low while SCK is low, otherwise the \overline{HOLD} function will not be invoked until the next SCK high to low transition. The 25XX640 must remain selected during this sequence. The SI, SCK, and SO pins are in a high impedance state during the time the device is paused and transitions on these pins will be ignored. To resume serial communication, \overline{HOLD} must be brought high while the SCK pin is low, otherwise serial communication will not resume. Lowering the \overline{HOLD} line at any time will tri-state the SO line.

25AA640/25LC640

3.0 FUNCTIONAL DESCRIPTION

3.1 Principles Of Operation

The 25XX640 is a 8192 byte Serial EEPROM designed to interface directly with the Serial Peripheral Interface (SPI) port of many of today's popular microcontroller families, including Microchip's PIC16C6X/7X microcontrollers. It may also interface with microcontrollers that do not have a built-in SPI port by using discrete I/O lines programmed properly with the software.

The 25XX640 contains an 8-bit instruction register. The device is accessed via the SI pin, with data being clocked in on the rising edge of SCK. The $\overline{\text{CS}}$ pin must be low and the $\overline{\text{HOLD}}$ pin must be high for the entire operation.

Table 3-1 contains a list of the possible instruction bytes and format for device operation. All instructions, addresses, and data are transferred MSB first, LSB last.

Data is sampled on the first rising edge of SCK after $\overline{\text{CS}}$ goes low. If the clock line is shared with other peripheral devices on the SPI bus, the user can assert the $\overline{\text{HOLD}}$ input and place the 25XX640 in 'HOLD' mode. After releasing the $\overline{\text{HOLD}}$ pin, operation will resume from the point when the $\overline{\text{HOLD}}$ was asserted.

3.2 Read Sequence

The device is selected by pulling $\overline{\text{CS}}$ low. The 8-bit read instruction is transmitted to the 25XX640 followed by the 16-bit address with the three MSB's of the address being don't care bits. After the correct read instruction and address are sent, the data stored in the memory at the selected address is shifted out on the SO pin. The data stored in the memory at the next address can be read sequentially by continuing to provide clock pulses. The internal address pointer is automatically incremented to the next higher address after each byte of data is shifted out. When the highest address is reached (1FFFh), the address counter rolls over to address 0000h allowing the read cycle to be continued indefinitely. The read operation is terminated by raising the $\overline{\text{CS}}$ pin (Figure 3-1).

3.3 Write Sequence

Prior to any attempt to write data to the 25XX640 array or status register, the write enable latch must be set by issuing the WREN instruction (Figure 3-4). This is done by setting $\overline{\text{CS}}$ low and then clocking out the proper instruction into the 25XX640. After all eight bits of the instruction are transmitted, the $\overline{\text{CS}}$ must be brought high to set the write enable latch. If the write operation is initiated immediately after the WREN instruction without $\overline{\text{CS}}$ being brought high, the data will not be written to the array because the write enable latch will not have been properly set.

Once the write enable latch is set, the user may proceed by setting the $\overline{\text{CS}}$ low, issuing a write instruction, followed by the address, and then the data to be written. Up to 32 bytes of data can be sent to the 25XX640 before a write cycle is necessary. The only restriction is that all of the bytes must reside in the same page. A page address begins with XXX0 0000 and ends with XXX1 1111. If the internal address counter reaches XXX1 1111 and the clock continues, the counter will roll back to the first address of the page and overwrite any data in the page that may have been written.

For the data to be actually written to the array, the $\overline{\text{CS}}$ must be brought high after the least significant bit (D0) of the n^{th} data byte has been clocked in. If $\overline{\text{CS}}$ is brought high at any other time, the write operation will not be completed. Refer to Figure 3-2 and Figure 3-3 for more detailed illustrations on the byte write sequence and the page write sequence respectively. While the write is in progress, the status register may be read to check the status of the WPEN, WIP, WEL, BP1, and BP0 bits (Figure 3-6). A read attempt of a memory array location will not be possible during a write cycle. When the write cycle is completed, the write enable latch is reset.

TABLE 3-1: INSTRUCTION SET

Instruction Name	Instruction Format	Description
READ	0000 0011	Read data from memory array beginning at selected address
WRITE	0000 0010	Write data to memory array beginning at selected address
WREN	0000 0110	Set the write enable latch (enable write operations)
WRDI	0000 0100	Reset the write enable latch (disable write operations)
RDSR	0000 0101	Read status register
WRSR	0000 0001	Write status register

FIGURE 3-1: READ SEQUENCE

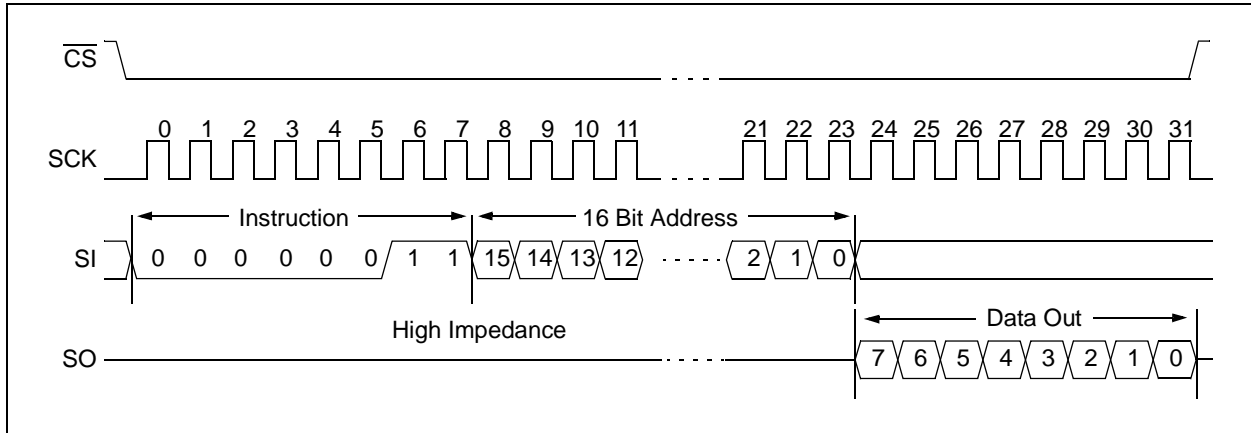


FIGURE 3-2: BYTE WRITE SEQUENCE

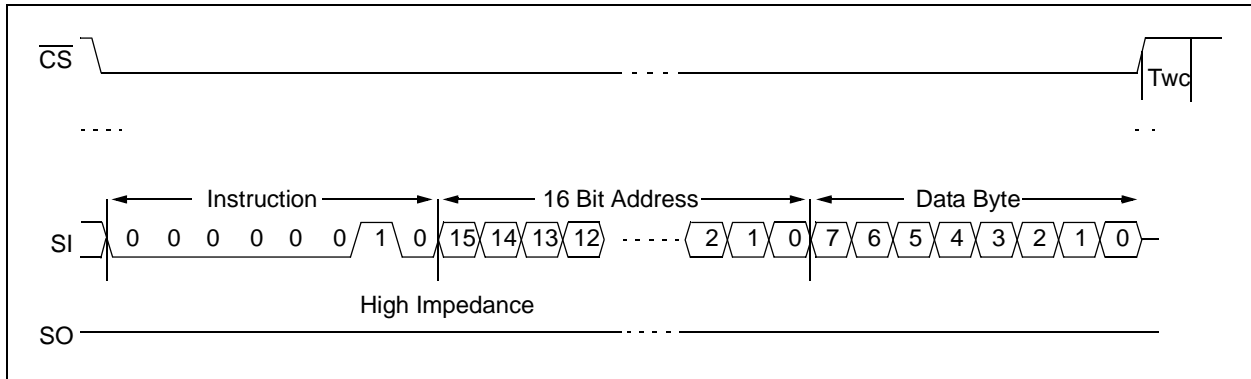
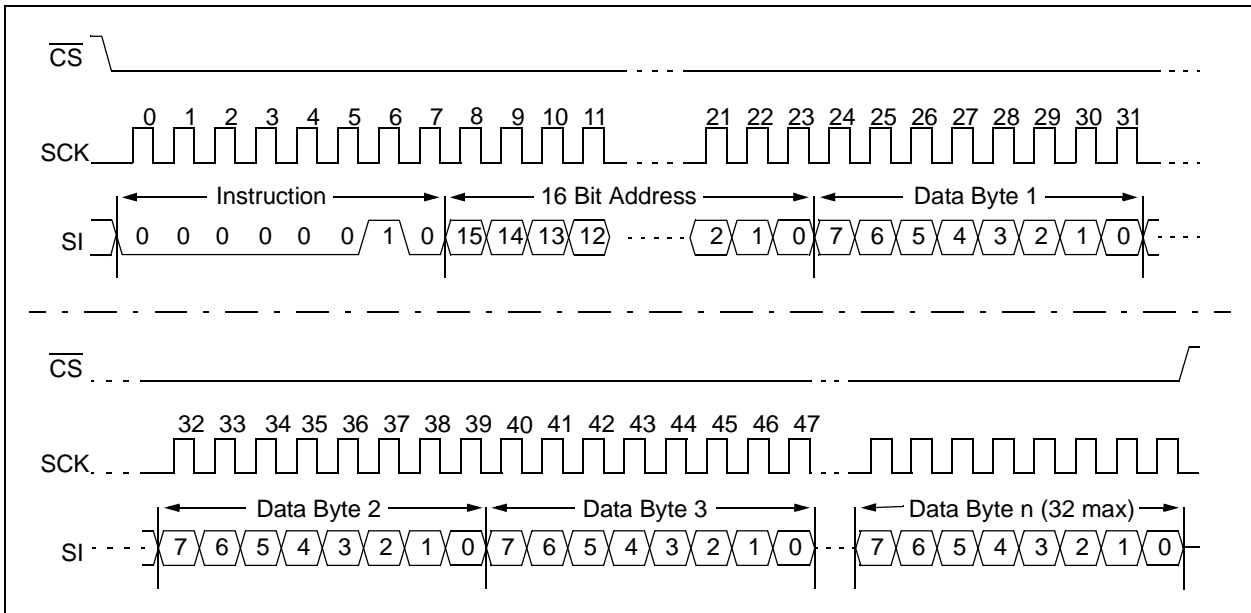


FIGURE 3-3: PAGE WRITE SEQUENCE



25AA640/25LC640

3.4 Write Enable (WREN) and Write Disable (WRDI)

The 25XX640 contains a write enable latch. See Table 3-3 for the Write Protect Functionality Matrix. This latch must be set before any write operation will be completed internally. The WREN instruction will set the latch, and the WRDI will reset the latch.

The following is a list of conditions under which the write enable latch will be reset:

- Power-up
- WRDI instruction successfully executed
- WRSR instruction successfully executed
- WRITE instruction successfully executed

FIGURE 3-4: WRITE ENABLE SEQUENCE

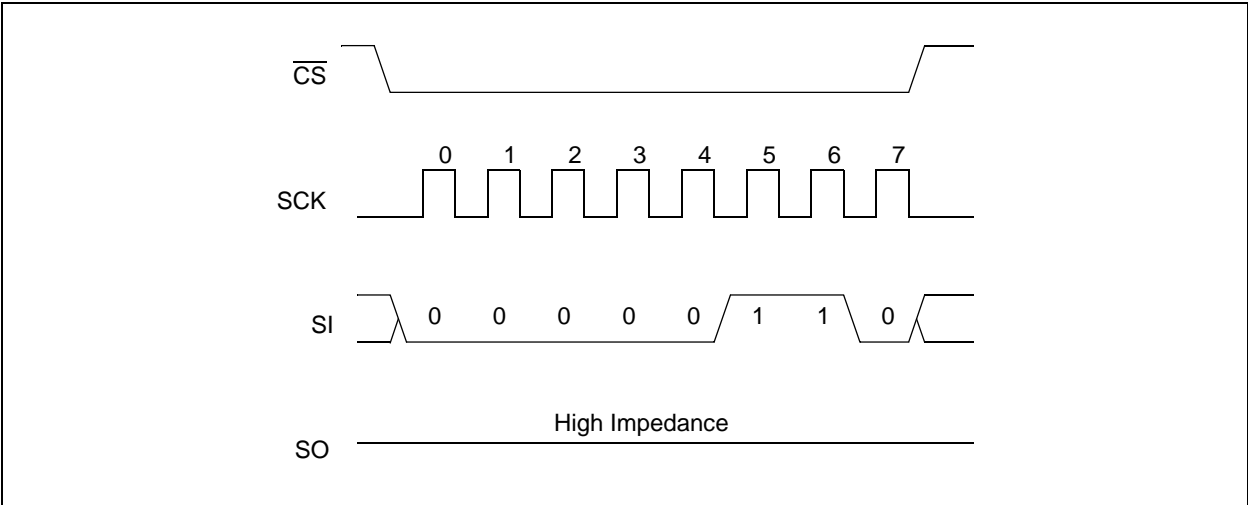
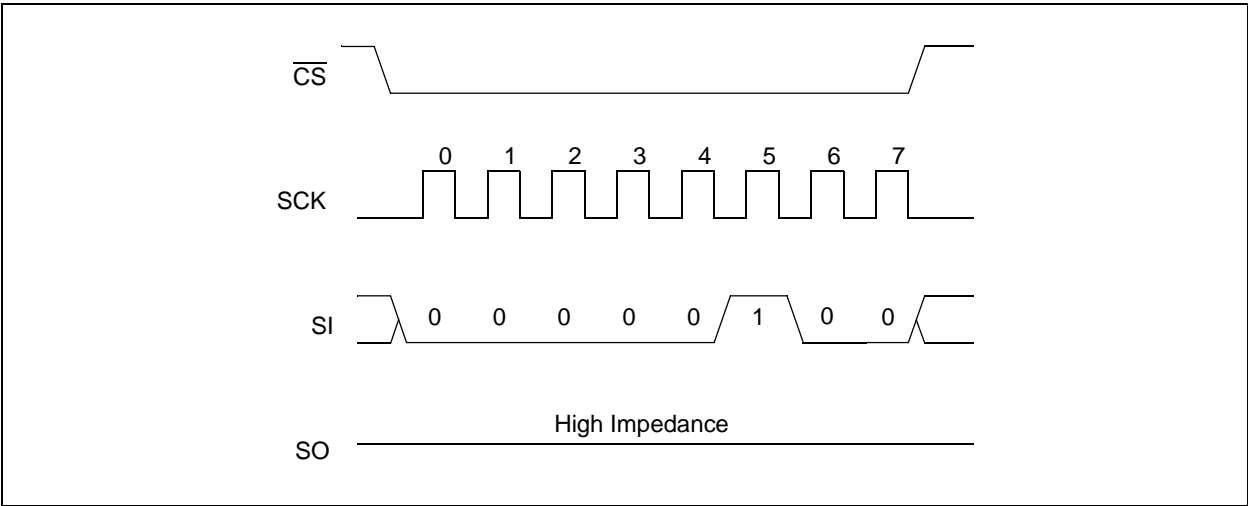


FIGURE 3-5: WRITE DISABLE SEQUENCE



3.5 Read Status Register (RDSR)

The Read Status Register (RDSR) instruction provides access to the status register. The status register may be read at any time, even during a write cycle. The status register is formatted as follows:

7	6	5	4	3	2	1	0
WPEN	X	X	X	BP1	BP0	WEL	WIP

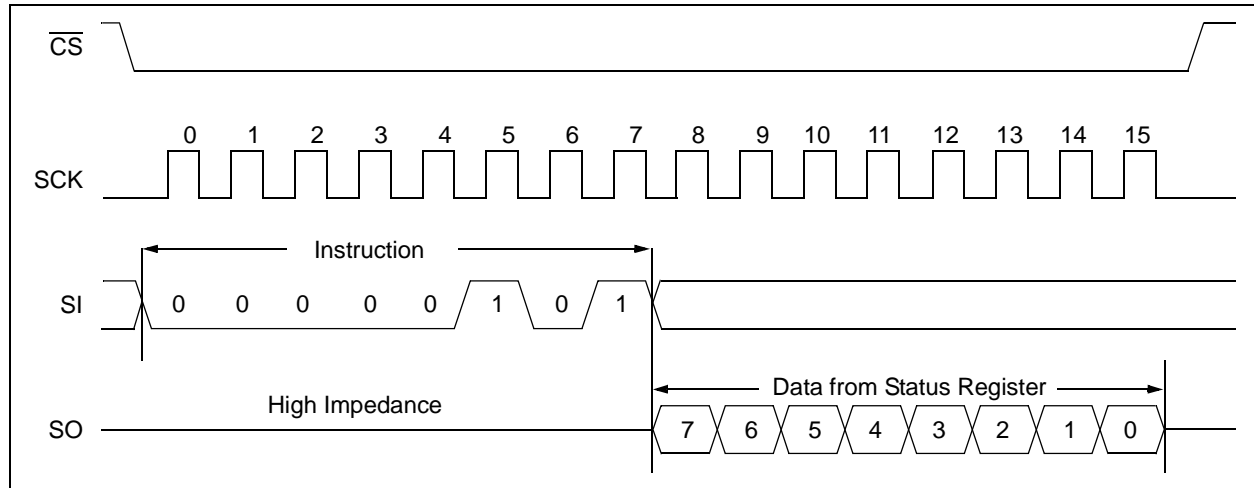
The **Write-In-Process (WIP)** bit indicates whether the 25XX640 is busy with a write operation. When set to a '1', a write is in progress, when set to a '0', no write is in progress. This bit is read only.

The **Write Enable Latch (WEL)** bit indicates the status of the write enable latch. When set to a '1', the latch allows writes to the array and status register, when set to a '0', the latch prohibits writes to the array and status register. The state of this bit can always be updated via the WREN or WRDI commands regardless of the state of write protection on the status register. This bit is read only.

The **Block Protection (BP0 and BP1)** bits indicate which blocks are currently write protected. These bits are set by the user issuing the WRSR instruction. These bits are non-volatile.

See Figure 3-6 for RDSR timing sequence.

FIGURE 3-6: READ STATUS REGISTER TIMING SEQUENCE



3.6 Write Status Register (WRSR)

The Write Status Register (WRSR) instruction allows the user to select one of four levels of protection for the array by writing to the appropriate bits in the status register. The array is divided up into four segments. The user has the ability to write protect none, one, two, or all four of the segments of the array. The partitioning is controlled as shown in Table 3-2.

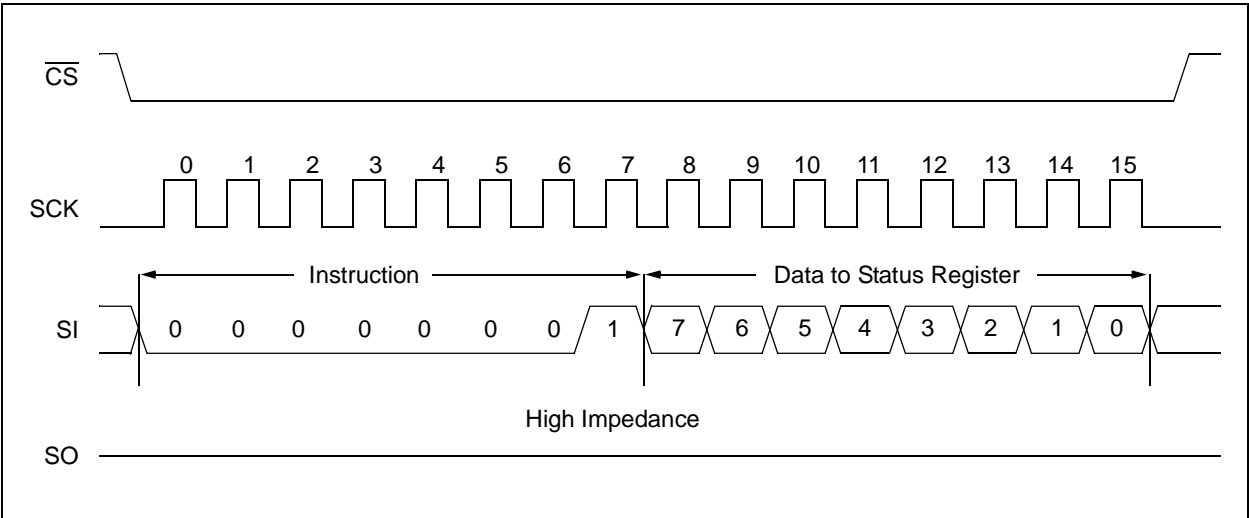
The **Write Protect Enable (WPEN)** bit is a non-volatile bit that is available as an enable bit for the \overline{WP} pin. The Write Protect (\overline{WP}) pin and the Write Protect Enable (WPEN) bit in the status register control the programmable hardware write protect feature. Hardware write protection is enabled when \overline{WP} pin is low and the WPEN bit is high. Hardware write protection is disabled when either the \overline{WP} pin is high or the WPEN bit is low. When the chip is hardware write protected, only writes to non-volatile bits in the status register are disabled. See Table 3-3 for a matrix of functionality on the WPEN bit.

See Figure 3-7 for WRSR timing sequence.

TABLE 3-2: ARRAY PROTECTION

BP1	BP0	Array Addresses Write Protected
0	0	none
0	1	upper 1/4 (1800h - 1FFFh)
1	0	upper 1/2 (1000h - 1FFFh)
1	1	all (0000h - 1FFFh)

FIGURE 3-7: WRITE STATUS REGISTER TIMING SEQUENCE



3.7 Data Protection

The following protection has been implemented to prevent inadvertent writes to the array:

- The write enable latch is reset on power-up
- A write enable instruction must be issued to set the write enable latch
- After a byte write, page write, or status register write, the write enable latch is reset
- \overline{CS} must be set high after the proper number of clock cycles to start an internal write cycle
- Access to the array during an internal write cycle is ignored and programming is continued

3.8 Power-On-State

The 25XX640 powers on in the following state:

- The device is in low power standby mode ($\overline{CS} = 1$)
- The write enable latch is reset
- SO is in high impedance state
- A high to low transition on \overline{CS} is required to enter the active state

TABLE 3-3: WRITE PROTECT FUNCTIONALITY MATRIX

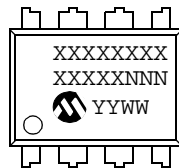
WPEN	\overline{WP}	WEL	Protected Blocks	Unprotected Blocks	Status Register
X	X	0	Protected	Protected	Protected
0	X	1	Protected	Writable	Writable
1	Low	1	Protected	Writable	Protected
X	High	1	Protected	Writable	Writable

25AA640/25LC640

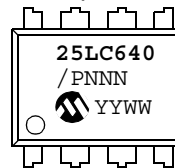
4.0 PACKAGING INFORMATION

4.1 Package Marking Information

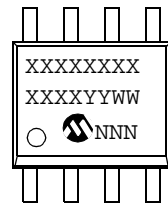
8-Lead PDIP (300 mil)



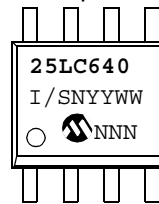
Example:



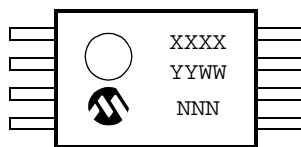
8-Lead SOIC (150 mil)



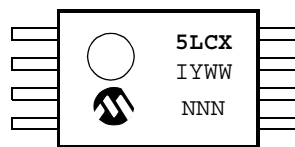
Example:



8-Lead TSSOP



Example:

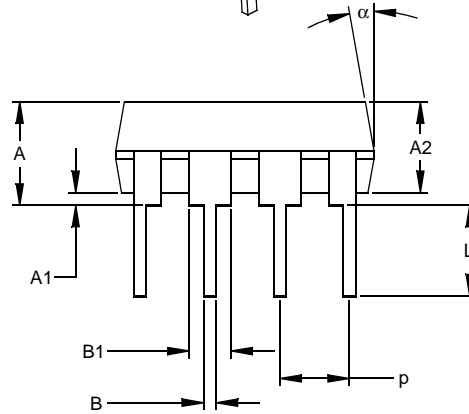
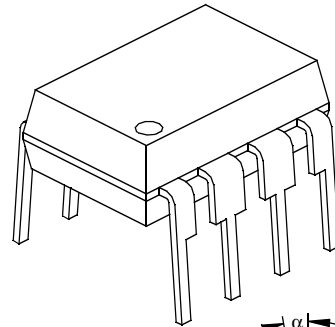
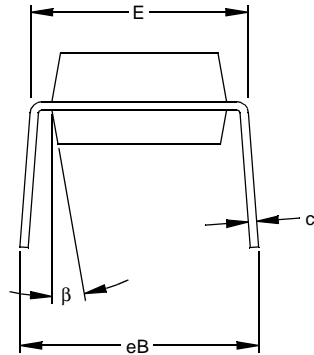
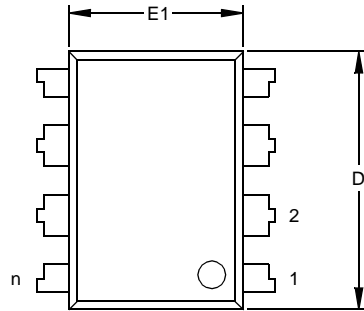


Legend:	XX...X	Customer specific information*
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code

Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.
--------------	--

* Standard marking consists of Microchip part number, year code, week code, traceability code (facility code, mask rev#, and assembly code). For marking beyond this, certain price adders apply. Please check with your Microchip Sales Office.

8-Lead Plastic Dual In-line (P) – 300 mil (PDIP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter

§ Significant Characteristic

Notes:

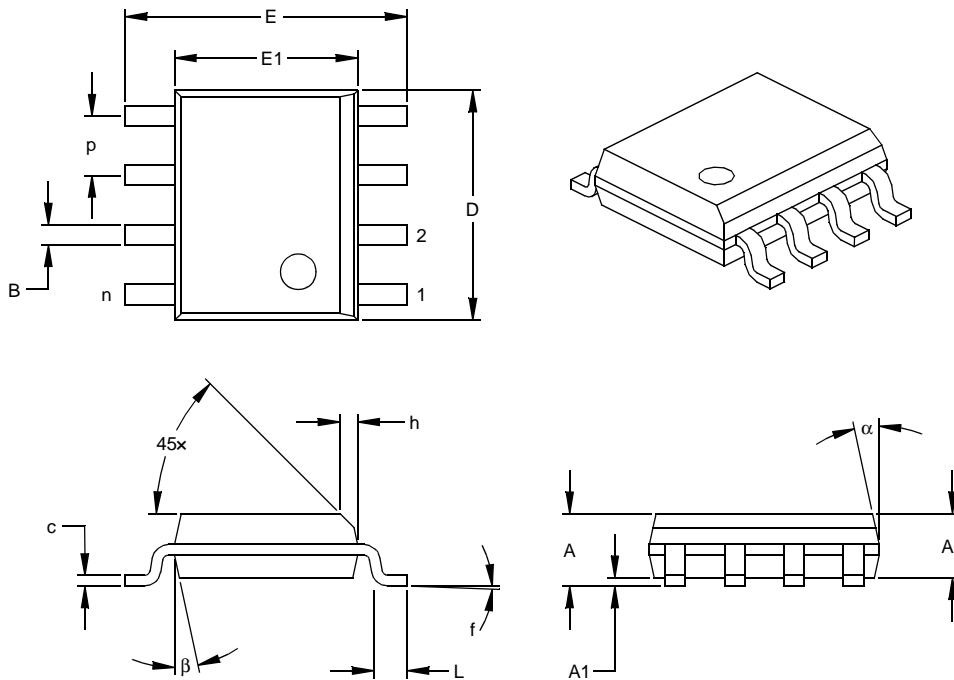
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-018

25AA640/25LC640

8-Lead Plastic Small Outline (SN) – Narrow, 150 mil (SOIC)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.050			1.27	
Overall Height	A	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	f	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter

§ Significant Characteristic

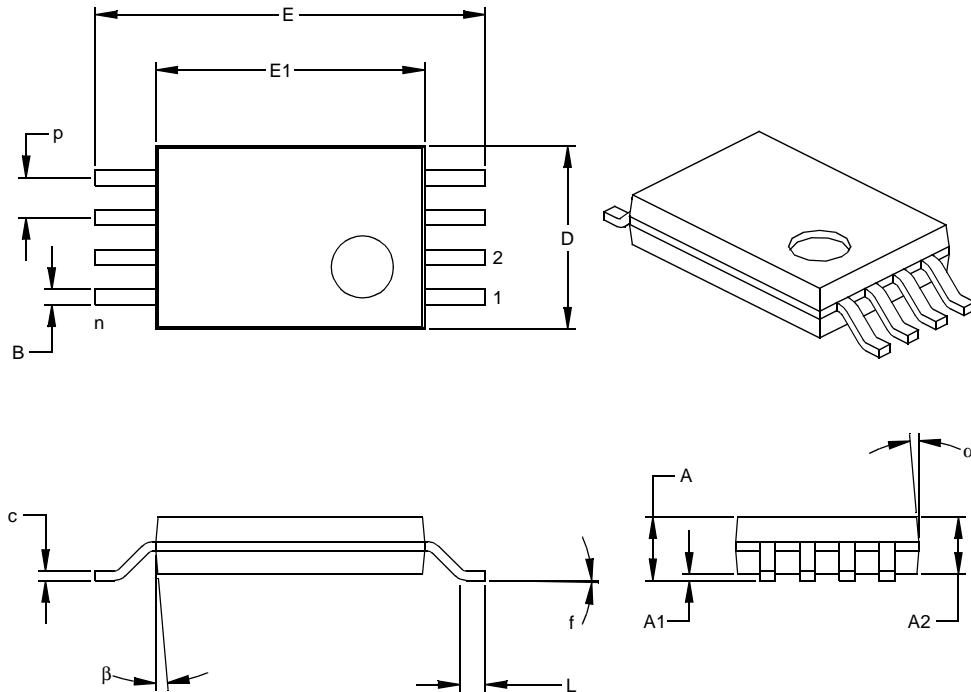
Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-012

Drawing No. C04-057

8-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm (TSSOP)



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.026			0.65	
Overall Height	A			.043			1.10
Molded Package Thickness	A2	.033	.035	.037	0.85	0.90	0.95
Standoff §	A1	.002	.004	.006	0.05	0.10	0.15
Overall Width	E	.246	.251	.256	6.25	6.38	6.50
Molded Package Width	E1	.169	.173	.177	4.30	4.40	4.50
Molded Package Length	D	.114	.118	.122	2.90	3.00	3.10
Foot Length	L	.020	.024	.028	0.50	0.60	0.70
Foot Angle	f	0	4	8	0	4	8
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.007	.010	.012	0.19	0.25	0.30
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

JEDEC Equivalent: MO-153

Drawing No. C04-086

25AA640/25LC640

NOTES:

ON-LINE SUPPORT

Microchip provides on-line support on the Microchip World Wide Web (WWW) site.

The web site is used by Microchip as a means to make files and information easily available to customers. To view the site, the user must have access to the Internet and a web browser, such as Netscape or Microsoft Explorer. Files are also available for FTP download from our FTP site.

Connecting to the Microchip Internet Web Site

The Microchip web site is available by using your favorite Internet browser to attach to:

www.microchip.com

The file transfer site is available by using an FTP service to connect to:

<ftp://ftp.microchip.com>

The web site and file transfer site provide a variety of services. Users may download files for the latest Development Tools, Data Sheets, Application Notes, User's Guides, Articles and Sample Programs. A variety of Microchip specific business information is also available, including listings of Microchip sales offices, distributors and factory representatives. Other data available for consideration is:

- Latest Microchip Press Releases
- Technical Support Section with Frequently Asked Questions
- Design Tips
- Device Errata
- Job Postings
- Microchip Consultant Program Member Listing
- Links to other useful web sites related to Microchip Products
- Conferences for products, Development Systems, technical information and more
- Listing of seminars and events

Systems Information and Upgrade Hot Line

The Systems Information and Upgrade Line provides system users a listing of the latest versions of all of Microchip's development systems software products. Plus, this line provides information on how customers can receive any currently available upgrade kits. The Hot Line Numbers are:

1-800-755-2345 for U.S. and most of Canada, and

1-480-792-7302 for the rest of the world.

013001

25AA640/25LC640

READER RESPONSE

It is our intention to provide you with the best documentation possible to ensure successful use of your Microchip product. If you wish to provide your comments on organization, clarity, subject matter, and ways in which our documentation can better serve you, please FAX your comments to the Technical Publications Manager at (480) 792-4150.

Please list the following information, and use this outline to provide us with your comments about this Data Sheet.

To: Technical Publications Manager
RE: Reader Response
From: Name _____
Company _____
Address _____
City / State / ZIP / Country _____
Telephone: (_____) _____ - _____ FAX: (_____) _____ - _____

Application (optional):

Would you like a reply? ___Y ___N

Device: **25AA640/25LC640** Literature Number: **DS21223E**

Questions:

1. What are the best features of this document?

2. How does this document meet your hardware and software development needs?

3. Do you find the organization of this data sheet easy to follow? If not, why?

4. What additions to the data sheet do you think would enhance the structure and subject?

5. What deletions from the data sheet could be made without affecting the overall usefulness?

6. Is there any incorrect or misleading information (what and where)?

7. How would you improve this document?

8. How would you improve our software, systems, and silicon products?

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.		X	/XX
Device		Temperature Range	Package
Device	25AA640:	64K bit 1.8V SPI Serial EEPROM	
	25AA640T:	64K bit 1.8V SPI Serial EEPROM (Tape and Reel)	
	25AA640X:	64K bit 1.8V SPI Serial EEPROM in alternate pinout (ST only)	
	25AA640XT:	64K bit 1.8V SPI Serial EEPROM in alternate pinout Tape and Reel (ST only)	
	25LC640:	64K bit 2.5V SPI Serial EEPROM	
	25LC640T:	64K bit 2.5V SPI Serial EEPROM (Tape and Reel)	
	25LC640X:	64K bit 2.5V SPI Serial EEPROM in alternate pinout (ST only)	
	25LC640XT:	64K bit 2.5V SPI Serial EEPROM in alternate pinout Tape and Reel (ST only)	
Temperature Range	I	=	-40°C to +85°C
	E	=	-40°C to +125°C
Package	P	=	Plastic DIP (300 mil Body), 8-lead
	SN	=	Plastic SOIC (150 mil Body), 8-lead
	ST	=	Plastic TSSOP (4.4 mm Body), 8-lead

Examples:

- a) 25AA640-I/SN: Industrial Temp., SOIC package
- b) 25AA640T-I/SN: Tape and Reel, Industrial Temp., SOIC package
- c) 25AA640-I/ST: Industrial Temp., TSSOP package
- a) 25LC640-I/SN: Industrial Temp., SOIC package
- b) 25LC640T-I/SN: Tape and Reel, Industrial Temp., SOIC package
- c) 25LC640X-I/ST: Alternate Pinout, Industrial Temp., TSSOP package

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
3. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

New Customer Notification System

Register on our web site (www.microchip.com/cn) to receive the most current information on our products.

25AA040/25LC040

NOTES:

Information contained in this publication regarding device applications and the like is intended through suggestion only and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. No representation or warranty is given and no liability is assumed by Microchip Technology Incorporated with respect to the accuracy or use of such information, or infringement of patents or other intellectual property rights arising from such use or otherwise. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, under any intellectual property rights.

Trademarks


The Microchip name and logo, the Microchip logo, PIC, PICmicro, PICMASTER, PICSTART, PRO MATE, KEELOQ, SEEVAL, MPLAB and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

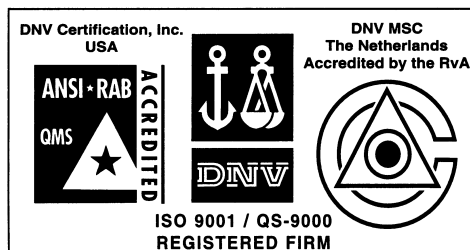
Total Endurance, ICSP, In-Circuit Serial Programming, Filter-Lab, MXDEV, microID, *FlexROM*, *fuzzyLAB*, MPASM, MPLINK, MPLIB, PICC, PICDEM, PICDEM.net, ICEPIC, Migratable Memory, FanSense, ECONOMONITOR, Select Mode and microPort are trademarks of Microchip Technology Incorporated in the U.S.A.

Serialized Quick Term Programming (SQTP) is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2001, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.



Microchip received QS-9000 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona in July 1999. The Company's quality system processes and procedures are QS-9000 compliant for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs and microperipheral products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001 certified.



WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office

2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200 Fax: 480-792-7277
Technical Support: 480-792-7627
Web Address: <http://www.microchip.com>

Rocky Mountain

2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7966 Fax: 480-792-7456

Atlanta

500 Sugar Mill Road, Suite 200B
Atlanta, GA 30350
Tel: 770-640-0034 Fax: 770-640-0307

Austin - Analog

13740 North Highway 183
Building J, Suite 4
Austin, TX 78750
Tel: 512-257-3370 Fax: 512-257-8526

Boston

2 Lan Drive, Suite 120
Westford, MA 01886
Tel: 978-692-3848 Fax: 978-692-3821

Boston - Analog

Unit A-8-1 Millbrook Tarry Condominium
97 Lowell Road
Concord, MA 01742
Tel: 978-371-6400 Fax: 978-371-0050

Chicago

333 Pierce Road, Suite 180
Itasca, IL 60143
Tel: 630-285-0071 Fax: 630-285-0075

Dallas

4570 Westgrove Drive, Suite 160
Addison, TX 75001
Tel: 972-818-7423 Fax: 972-818-2924

Dayton

Two Prestige Place, Suite 130
Miamisburg, OH 45342
Tel: 937-291-1654 Fax: 937-291-9175

Detroit

Tri-Atria Office Building
32255 Northwestern Highway, Suite 190
Farmington Hills, MI 48334
Tel: 248-538-2250 Fax: 248-538-2260

Los Angeles

18201 Von Karman, Suite 1090
Irvine, CA 92612
Tel: 949-263-1888 Fax: 949-263-1338

New York

150 Motor Parkway, Suite 202
Hauppauge, NY 11788
Tel: 631-273-5305 Fax: 631-273-5335

San Jose

Microchip Technology Inc.
2107 North First Street, Suite 590
San Jose, CA 95131
Tel: 408-436-7950 Fax: 408-436-7955

Toronto

6285 Northam Drive, Suite 108
Mississauga, Ontario L4V 1X5, Canada
Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Australia

Microchip Technology Australia Pty Ltd
Suite 22, 41 Rawson Street
Epping 2121, NSW
Australia
Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing

Microchip Technology Consulting (Shanghai)
Co., Ltd., Beijing Liaison Office
Unit 915
Bei Hai Wan Tai Bldg.
No. 6 Chaoyangmen Beidajie
Beijing, 100027, No. China
Tel: 86-10-85282100 Fax: 86-10-85282104

China - Chengdu

Microchip Technology Consulting (Shanghai)
Co., Ltd., Chengdu Liaison Office
Rm. 2401, 24th Floor,
Ming Xing Financial Tower
No. 88 TIDU Street
Chengdu 610016, China
Tel: 86-28-6766200 Fax: 86-28-6766599

China - Fuzhou

Microchip Technology Consulting (Shanghai)
Co., Ltd., Fuzhou Liaison Office
Rm. 531, North Building
Fujian Foreign Trade Center Hotel
73 Wusi Road
Fuzhou 350001, China
Tel: 86-591-7557563 Fax: 86-591-7557572

China - Shanghai

Microchip Technology Consulting (Shanghai)
Co., Ltd.
Room 701, Bldg. B
Far East International Plaza
No. 317 Xian Xia Road
Shanghai, 200051
Tel: 86-21-6275-5700 Fax: 86-21-6275-5060

China - Shenzhen

Microchip Technology Consulting (Shanghai)
Co., Ltd., Shenzhen Liaison Office
Rm. 1315, 13/F, Shenzhen Kerry Centre,
Renminnan Lu
Shenzhen 518001, China
Tel: 86-755-2350361 Fax: 86-755-2366086

Hong Kong

Microchip Technology Hongkong Ltd.
Unit 901-6, Tower 2, Metroplaza
223 Hing Fong Road
Kwai Fong, N.T., Hong Kong
Tel: 852-2401-1200 Fax: 852-2401-3431

India

Microchip Technology Inc.
India Liaison Office
Divyasree Chambers
1 Floor, Wing A (A3/A4)
No. 11, O'Shaughnessey Road
Bangalore, 560 025, India
Tel: 91-80-2290061 Fax: 91-80-2290062

Japan

Microchip Technology Japan K.K.
Benex S-1 6F
3-18-20, Shinyokohama
Kohoku-Ku, Yokohama-shi
Kanagawa, 222-0033, Japan
Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea

Microchip Technology Korea
168-1, Youngbo Bldg. 3 Floor
Samsung-Dong, Kangnam-Ku
Seoul, Korea 135-882
Tel: 82-2-554-7200 Fax: 82-2-558-5934

Singapore

Microchip Technology Singapore Pte Ltd.
200 Middle Road
#07-02 Prime Centre
Singapore, 188980
Tel: 65-334-8870 Fax: 65-334-8850

Taiwan

Microchip Technology Taiwan
11F-3, No. 207
Tung Hua North Road
Taipei, 105, Taiwan
Tel: 886-2-2717-7175 Fax: 886-2-2545-0139

EUROPE

Denmark

Microchip Technology Denmark ApS
Regus Business Centre
Lautrup høj 1-3
Ballerup DK-2750 Denmark
Tel: 45 4420 9895 Fax: 45 4420 9910

France

Arizona Microchip Technology SARL
Parc d'Activite du Moulin de Massy
43 Rue du Saule Trapu
Batiment A - 1er Etage
91300 Massy, France
Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany

Arizona Microchip Technology GmbH
Gustav-Heinemann Ring 125
D-81739 Munich, Germany
Tel: 49-89-627-144 0 Fax: 49-89-627-144-44

Germany - Analog

Lochamer Strasse 13
D-82152 Martinsried, Germany
Tel: 49-89-895650-0 Fax: 49-89-895650-22

Italy

Arizona Microchip Technology SRL
Centro Direzionale Colleoni
Palazzo Taurus 1 V. Le Colleoni 1
20041 Agrate Brianza
Milan, Italy
Tel: 39-039-65791-1 Fax: 39-039-6899883

United Kingdom

Arizona Microchip Technology Ltd.
505 Eskdale Road
Winnersh Triangle
Wokingham
Berkshire, England RG41 5TU
Tel: 44 118 921 5869 Fax: 44-118 921-5820

08/01/01